



ECE695: Reliability Physics of Nano-Transistors Lecture 1: Reliability of Nanoelectronic Devices

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Outline of lecture 1

- I. Evolving Landscape of Electronics
- 2. Performance, Variability, and Reliability
- 3. Classification of Reliability
- 4. Course Information
- 5. Conclusions

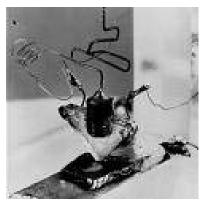
Technology & transistors in electronics

Vacuum Tubes



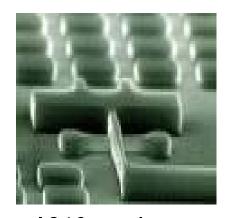
1906-1950s

Bipolar



1947-1980s

MOSFET



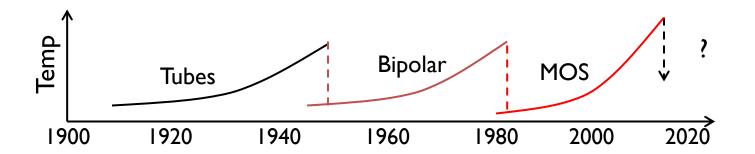
1960-until now

Now ??

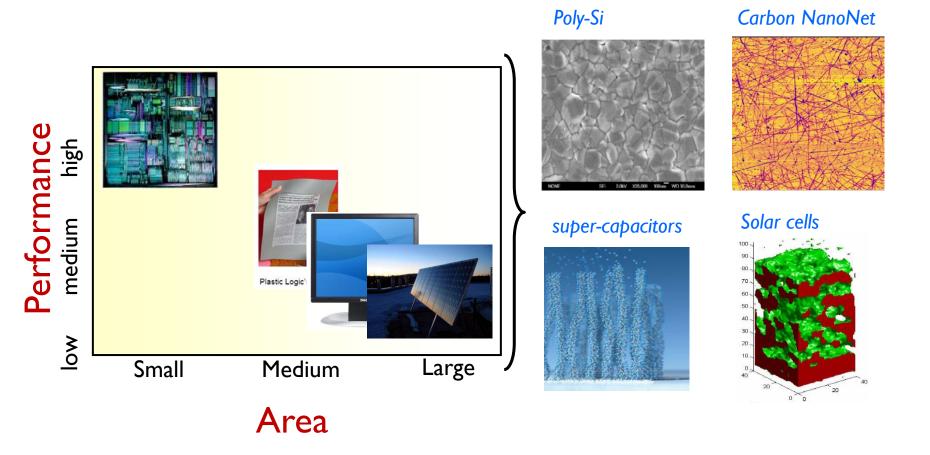
Sub-60 mV/dec Switches

Bio Sensors

Displays



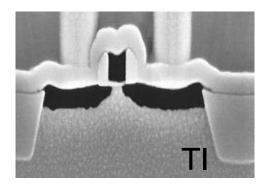
Landscape of electronics in evolving



Electronics is a vibrant industry with many new applications

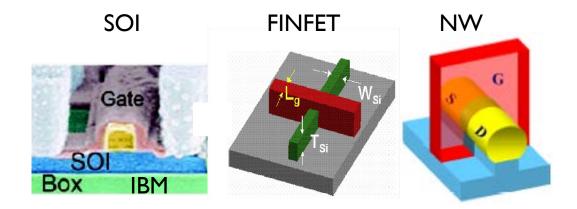
Evolution in microelectronics

Mobility improvement by new materials (lon)



- → Strained silicon
- Ge channel
- → III-V materials

Electrostatics improvement by new device geometry (Ion/Ioff)

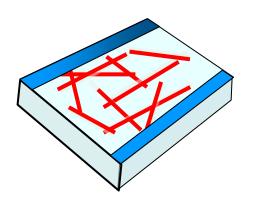


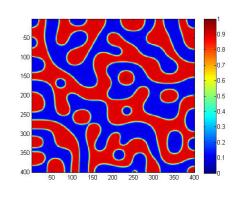
- → Silicon on insulator (SOI)
- → Tri-gate (e.g. FINFET)
- → Surround gate (e.g. NW)

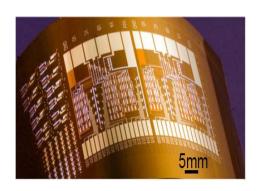
Evolution in large area electronics

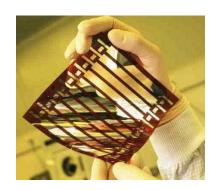
Flexible Electronics

Organic Solar Cells









New materials for novel devices enhance performance, but also accentuate reliability concerns

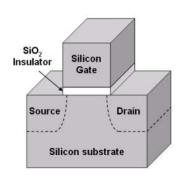
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- I. Landscape of Electronics: Performance
- 2. Performance, Variability, and Reliability
- 3. Classification of Reliability
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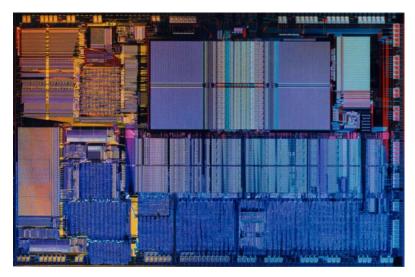
Uniformity of Components in Systems



Maudslay (1800), Whitworth (1841), Sellers (1864)

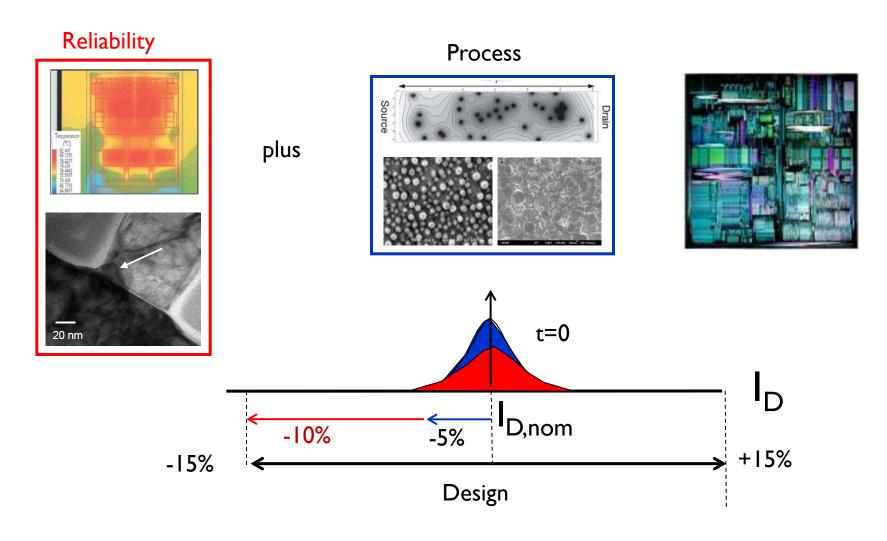






Building large systems presumes uniformity of components

Process, reliability, and design



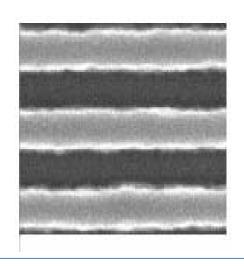
We do not have too much margin

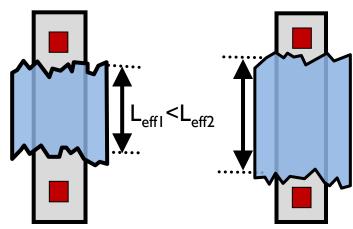
Process variations in scaled

I) Line Edge Roughness



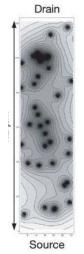
Dev 2

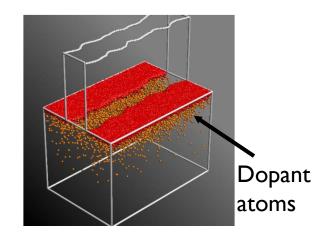


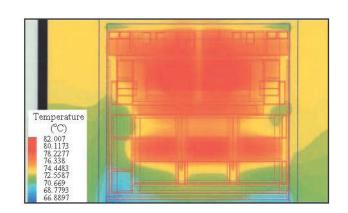


2) Random Dopant Fluctuations

3) Non-uniform Temperature

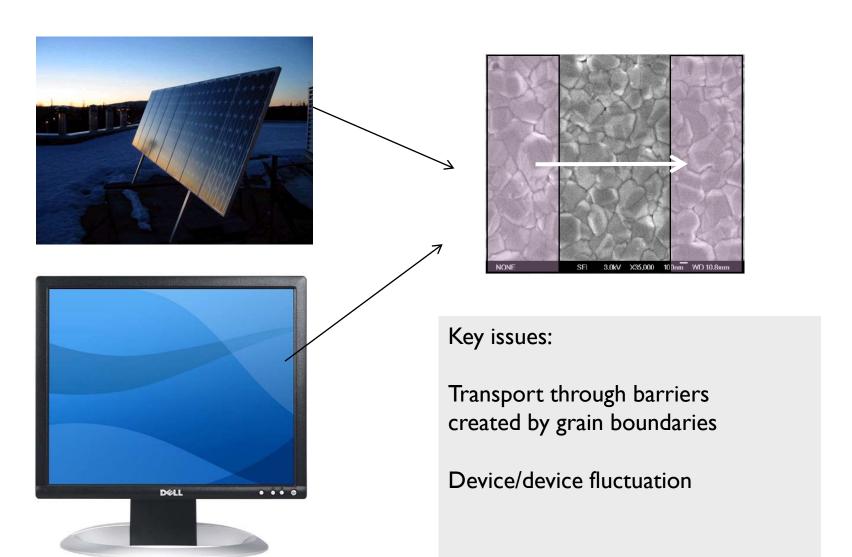






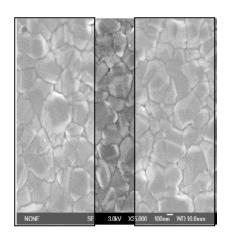
M. Hane, et. al., SISPAD 2003

Solar cells and display electronics

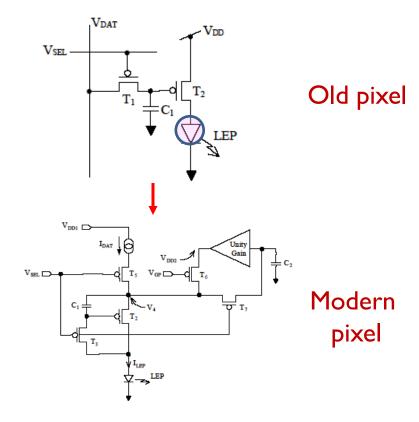


Process variation: thin film transistors

Modern poly TFT is reaching dimensions of a single grain

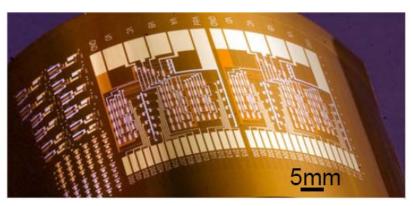


.... makes pixel design increasingly complicated



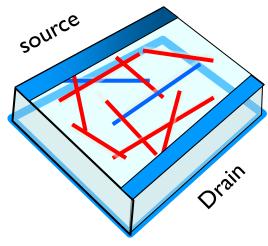
Simon Tam, IEDM, 2002

Flexible nanonet electronics

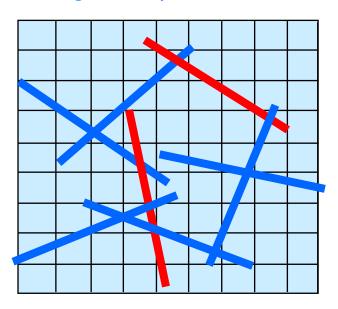


Cao, Nature, 2008

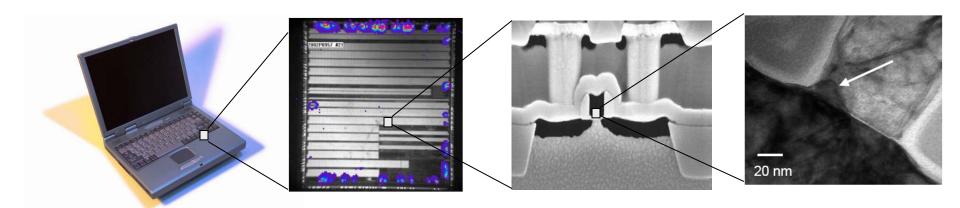
Heterogeneous percolation



Metallic and semiconducting tubes



Reliability: time dependent degradation



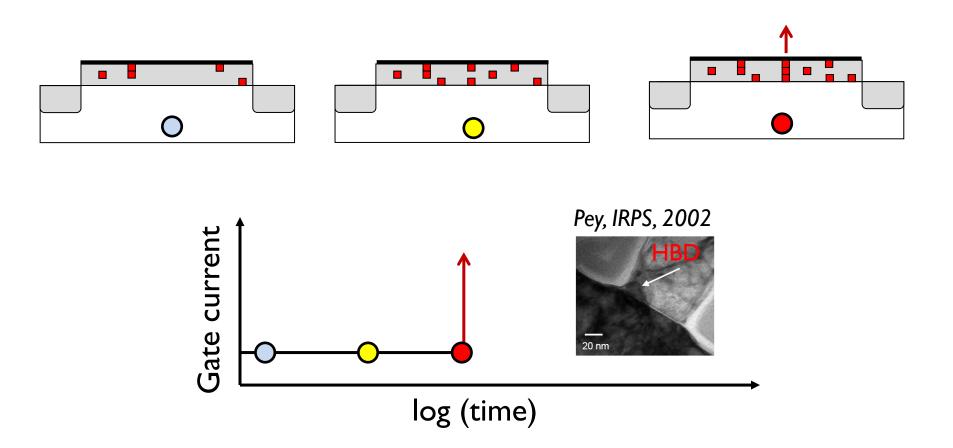
A manufacturer bets the company of the physics of reliability

... because the ICs operate in incredibly harsh conditions, turning on and off trillions of time during its lifetime

... because the lines can open, the source/drain can be shorted, the gate oxide can break

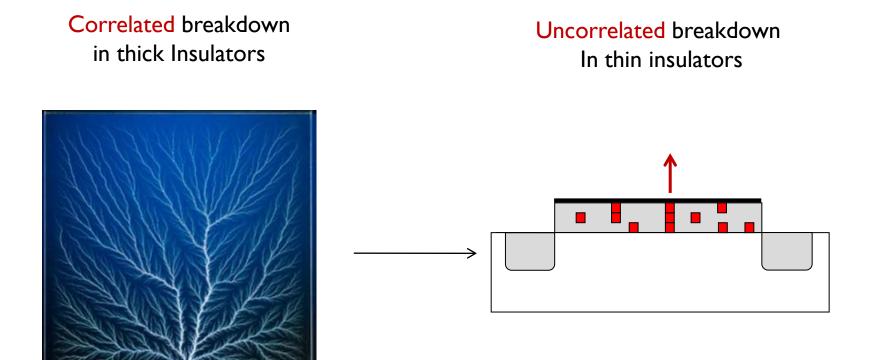
Design for reliability

Time dependent dielectric breakdown



Reliability: a stochastic process terminated by a threshold

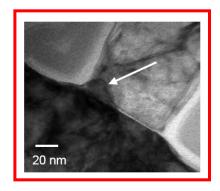
Reliability: correlation, power-laws, contacts



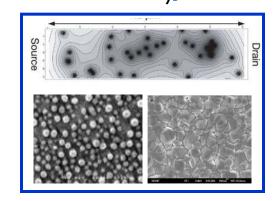
Theory of partially correlated breakdown is important and contacts define everything.

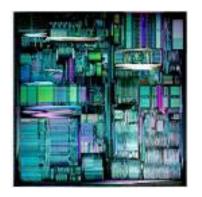
Equivalence between variability & reliability

Reliability

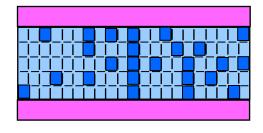


plus

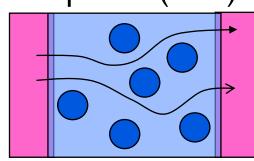




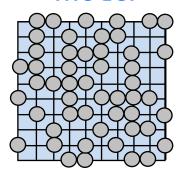
Side view (TDDB)



top view (RDF)



model



Spatial and temporal fluctuation should be considered with same framework ...

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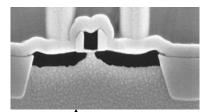
Reliability of nanotransistors

Transistor Reliability

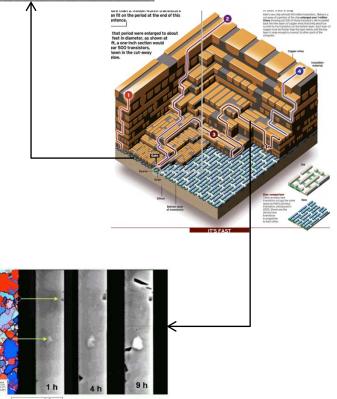
- Gate Dielectric Breakdown
- Negative Bias Temperature Instability
- Hot Carrier Degradation
- Radiation Induced damage

Interconnect Reliability

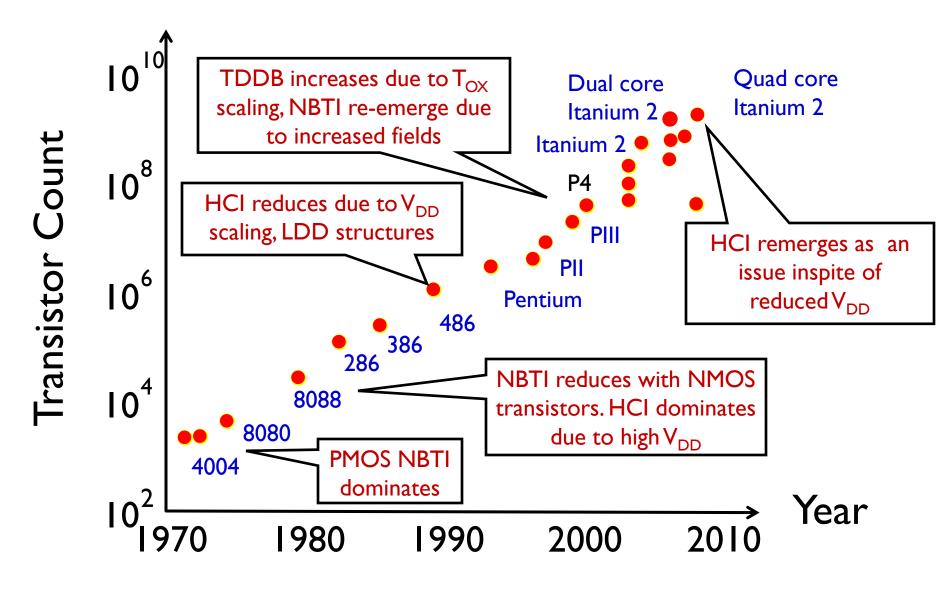
- Electro-migration/Stress-migration.
- Inter-level dielectric breakdown



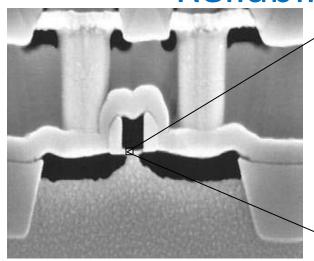
The Oregonian, 2008

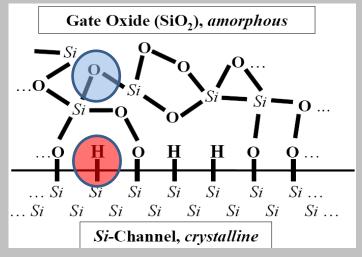


Scaling and reliability: A short history



Reliability and honding





Broken Si-H bonds

Negative Bias Temperature Instability (NBTI) Hot carrier degradation (HCI)

Broken Si-O bonds

Gate dielectric Breakdown (TDDB)
Electrostatic Discharge (ESD)
Radiation induced Gate Rupture (RBD)

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Course Information

Introduction to Reliability (3 Lectures) Physics of Defects (3 Lectures) Negative Bias Temperature Instability (6 lectures) ☐ Hot Carrier Degradation (4 lectures) Characterization Techniques (4 lectures) Gate Dielectric Breakdown (9 Lectures) Radiation Damage (5 lectures) ☐ Statistics and Backend Reliability (5 lectures)

Reference books

Fundamentals of Modern VLSI Devices

Taur and Ning, Cambridge University, 1998.

Advanced Semiconductor Fundamentals, 2nd Ed.

Pierret, Prentice Hall

Semiconductor Material and Device Characterization

D. Schroeder, John Wiley and Sons.

Lecture Notes and Review Papers

Class participation (10%), Homework (25%), Two exams (40%), and a Final report (15%)

A Word about references

Some references are included in the slides; for others, please refer to a comprehensive list of references included in the review papers posted at the website.

I have used a few figures from Google Images. The links are available in the reference pages. Let me know of any copyright issues.

A set of lecture notes on reliability are available at http://cobweb.ecn.purdue.edu/~ee650/handouts.htm

The 2009 Summer School notes posted at https://nanohub.org/resources/7168 could be useful.

A number of programs that were used to obtain the results of this tutorial are available from www.nanohub.org

Conclusions

- Modern electronics is developing rapidly with many new applications.
- ☐ Variability and reliability are two distinct and fundamental concerns of modern electronic devices.
- Reliability is fundamentally about a stochastic process terminated by a threshold. The process may be correlated or uncorrelated, and the evolution depends on boundary conditions.
- We will focus on reliability of nano-transistors. The theoretical and mathematical approaches are easily adapted to other electronic and nano-electronic components.